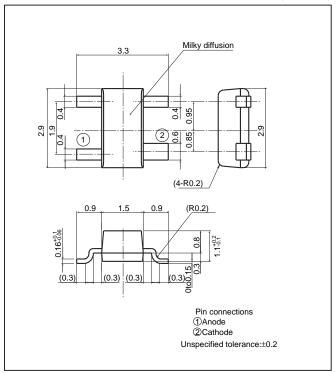
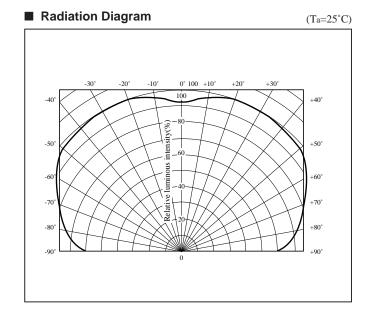
LT1□53A series

3.3×2.9mm, 1.1mm Thickness, Milky Diffusion Chip LED Devices

■ Outline Dimensions

(Unit: mm)





■ Absolute Maximum Ratings

 $(T_a=25^{\circ}C)$

											(1a=23 C)
Model No.	Radiation color	Radiation material	Power dissipation	Forward current IF	Peak forward current IFM*1	Derating factor (mA/°C)		Reverse voltage V _R	Operating temperature Storage temperature Topr Tstg		Soldering temperature ${T_{sol}}^{*2}$
			(mW)	(mA)	(mA)	DC	Pulse	(V)	(°C)	(°C)	(°C)
LT1P53A	Red	GaP	23	10	50	0.13	0.67	5	-25 to +85	-25 to +100	350
LT1D53A	Red	GaAsP on GaP	85	30	50	0.40	0.67	5	-25 to +85	-25 to +100	350
LT1S53A	Sunset orange	GaAsP on GaP	85	30	50	0.40	0.67	5	-25 to +85	-25 to +100	350
LT1H53A	Yellow	GaAsP on GaP	50	20	50	0.27	0.67	5	-25 to +85	-25 to +100	350
LT1E53A	Yellow-green	GaP	50	20	50	0.27	0.67	5	-25 to +85	-25 to +100	350
LT1K53A	Green	GaP	50	20	50	0.27	0.67	5	-25 to +85	-25 to +100	350

^{*1} Duty ratio=1/10, Pulse width=0.1ms

■ Electro-optical Characteristics

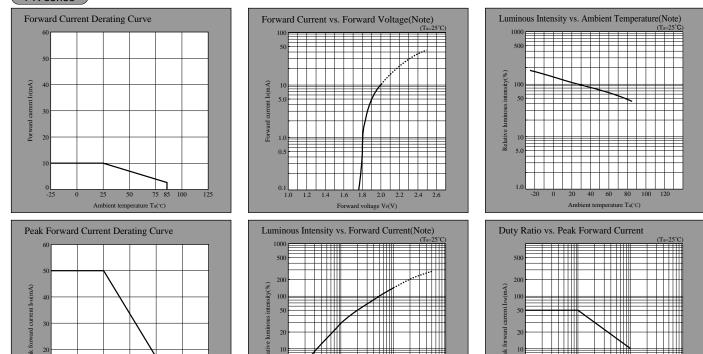
 $(T_a=25^{\circ}C)$

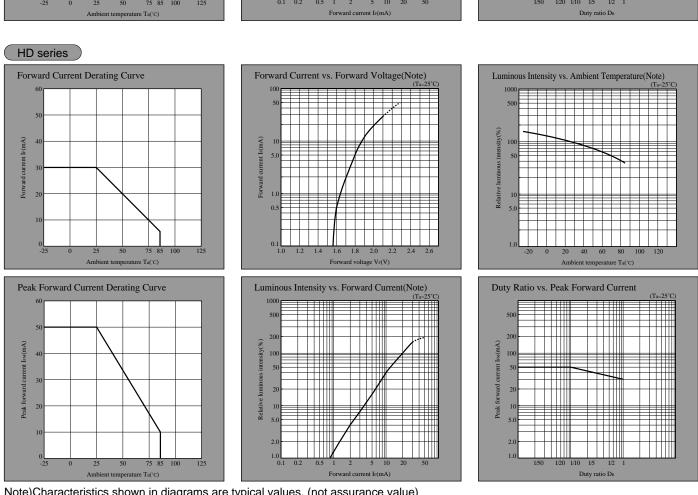
Lens type	Model No.	Forward voltage V _F (V)		Peak emission wavelength		Luminous intensity		Spectrum radiation bandwidth		Reverse current		Terminal capacitance		Page for
				$\lambda_p(nm)$	IF	Iv(mcd)	\mathbf{I}_{F}	$\Delta\lambda(nm)$	I_{F}	Ir(µA)	V_R	C _t (pF)	(MIL)	characteristics
		TYP	MAX	TYP	(mA)	TYP	(mA)	TYP	(mA)	MAX	(V)	TYP	(MHz)	diagrams
Milky diffusion	LT1P53A	1.9	2.3	695	5	1.4	5	100	5	10	4	55	1	\rightarrow
	LT1D53A	2.0	2.8	635	20	9.6	20	35	20	10	4	20	1	\rightarrow
	LT1S53A	2.0	2.8	610	20	7.8	20	35	20	10	4	15	1	\rightarrow
	LT1H53A	1.9	2.5	585	10	3.7	10	30	10	10	4	35	1	\rightarrow
	LT1E53A	1.85	2.5	565	10	4.8	10	30	10	10	4	35	1	\rightarrow
	LT1K53A	1.95	2.5	555	10	2.2	10	25	10	10	4	40	1	\rightarrow

⁽Notice) • In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.

^{*2} For 3s or less at the temperature of hand soldering. Temperature of reflow soldering is shown on the below page.

PR series





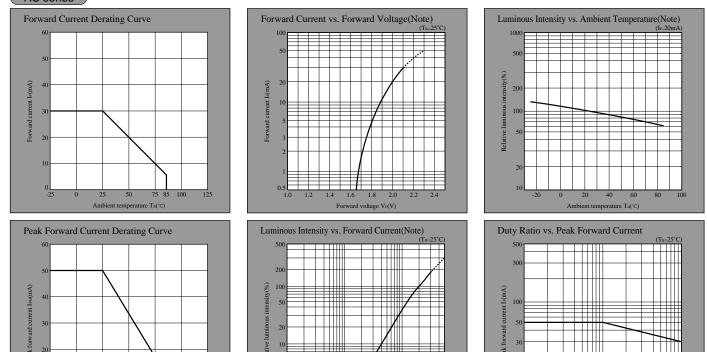
Note) Characteristics shown in diagrams are typical values. (not assurance value)

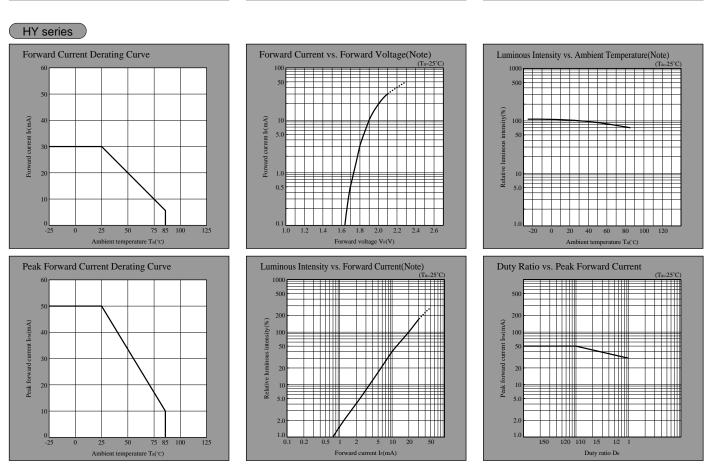
• In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.

(Internet) • Data for sharp's optoelectronic/power device is provided for internet.(Address http://www.sharp.co.jp/ecg/)

Ambient temperature Ta(°C)

HS series





Forward current I_F(mA)

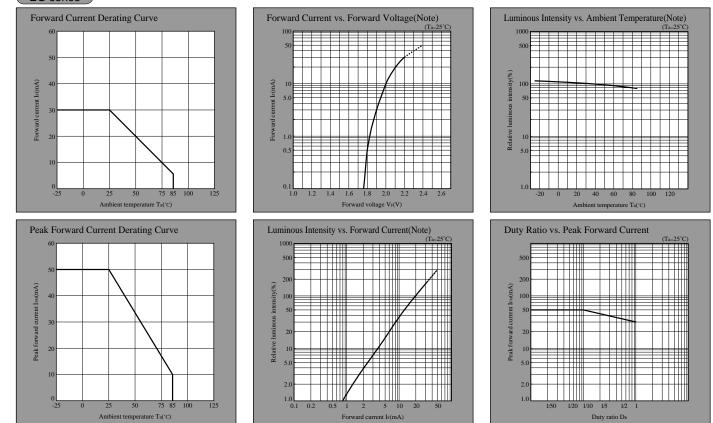
Duty ratio D_R

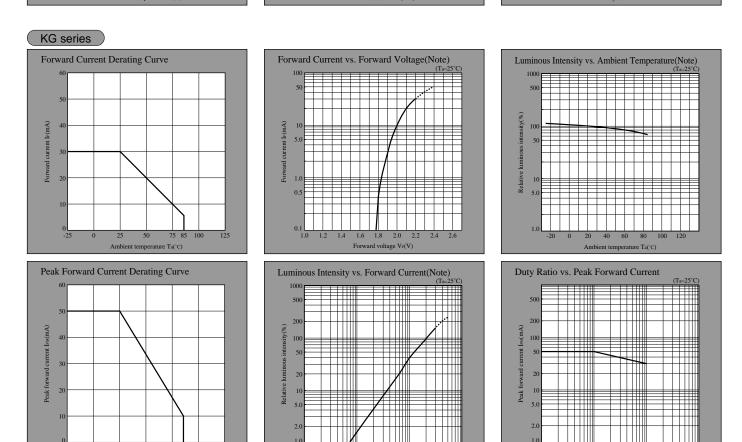
Note) Characteristics shown in diagrams are typical values. (not assurance value)

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(Internet) • Data for sharp's optoelectronic/power device is provided for internet (Address http://www.sharp.co.jp/ecg/)

EG series





Note) Characteristics shown in diagrams are typical values. (not assurance value)

Duty ratio DR

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